

# Foreword

## Special Issue on Transistors With Steep Subthreshold Swing for Low-Power Electronics

THE increasing power consumption of integrated circuits is today the main impediment to the density scaling of integrated circuit technology. The reduction of supply voltage is the most effective way to reduce power; however, using modern transistors voltage reduction is traded against reduced speed or limited by a rising off-state leakage, neither of which is desirable. A better tradeoff can be achieved if the fundamental current control mechanism provides a steep turn-on characteristic. Steep means better than 60 mV/decade at room temperature, the limit obtained by barrier lowering in a bipolar transistor or metal oxide semiconductor field effect transistor (MOSFET) when the current is dominated by the thermionic emission of carriers above the energy barrier in the base or channel region.

The intensity of experimental and theoretical efforts on steep transistors has been growing worldwide as technical impediments are systematically solved. Subthreshold swings less than 60 mV/decade have been experimentally demonstrated in tunnel field-effect transistors (TFETs) across a wide range of materials systems including carbon nanotubes, Si, and III-Vs. On-currents comparable to MOSFETs have been demonstrated with sub-half-volt supplies. TFETs have received the greatest attention thus far, but are one of a growing number of approaches for achieving steep transistor characteristics.

Our intent with this special issue was to consolidate the latest advances on steep swing transistors with an emphasis on TFETs since this technology is the most highly developed. The call for papers invited submissions that address advances in materials and process technologies, experimental techniques and characterization, modeling and simulation approaches, and design methodologies. We requested papers in: 1) steep transistor concepts; 2) materials and process development; 3) measurements and characterization; 4) modeling and simulations; and 5) device and circuit design.

The special issue begins with five invited papers to provide progress and perspective in the development of TFETs. Uygar Avci, Intel, and Eric Lind, University of Lund, summarize recent progress and current directions in III-V tunnel FETs. The topic of nanowire TFETs is extended in the paper by Qing-Tai Zhao, Forschungszentrum Jülich GmbH, based on the Si and SiGe nanowire systems. Marco Pala, IMEP-LaHC, discusses design options for heterojunction nanowire III-V TFETs based on full quantum 3D simulations. Finally, Peter Asbeck considers the performance of TFETs in low power microwave and mm-wave applications. The 13 contributed papers are divided into three broad themes: 1) device concepts; 2) experimental progress; and 3) modeling and circuit simulation.

The special issue meets our aim of providing a consolidation of the latest advancements in steep subthreshold swing technology. The papers also show that the field is still in an early stage with many competing approaches. Materials, processes, and device understanding is advancing as experiments and models advance. Early assessment of systems impact is giving designers a first look at transistors with the potential to outperform CMOS at low voltages.

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